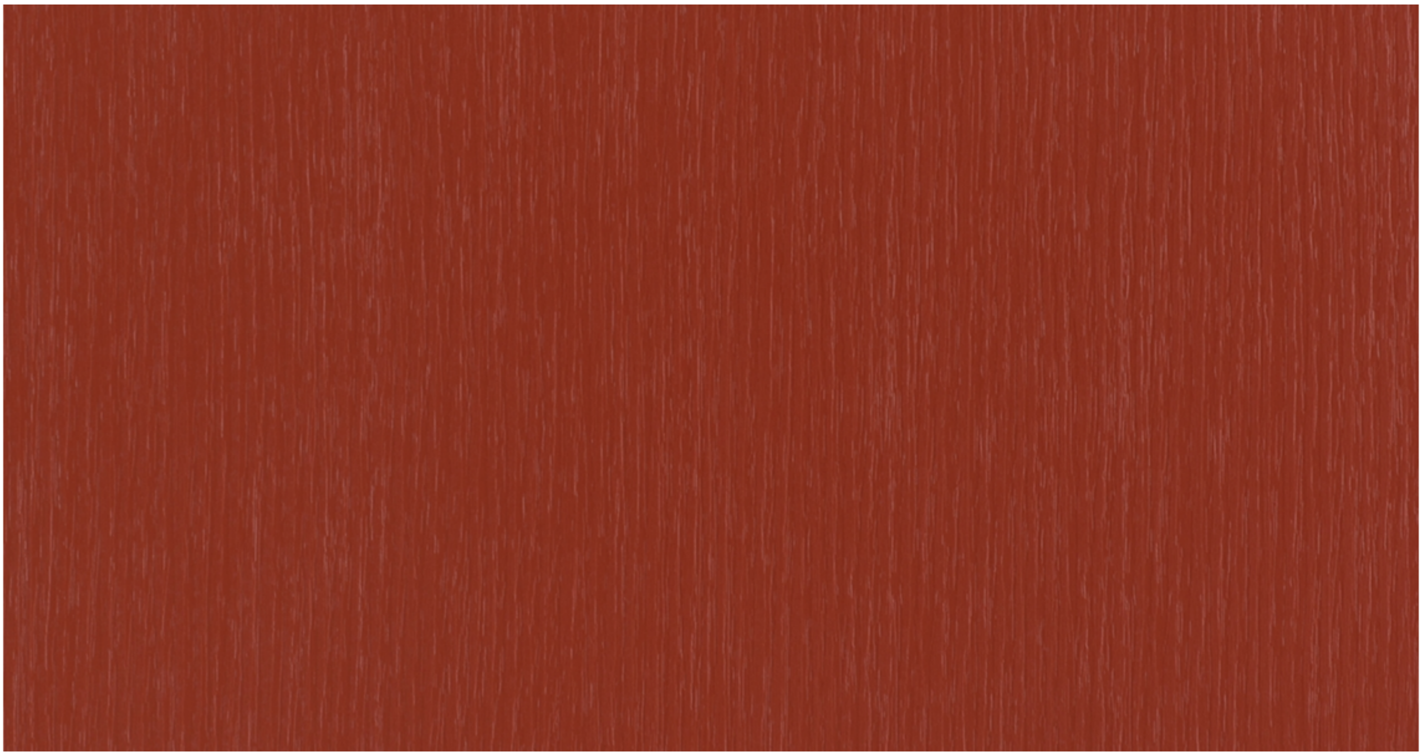
CLEAF



FACED PANEL

CEPPO
UB55

SUPPORT: Chipboard, MDF
FORMAT: 5600 x 2070 mm
THICKNESS: from 8 to 38 mm
TEXTURE ORIENTATION: Vertical
BACK TEXTURE: Ceppo
NOMINAL OVERTHICKNESS: +0.1 mm

LAMINATE

CEPPO
UB55

TYPE: HPL
FORMAT: 2760 x 2040 mm
THICKNESS: 0.9 mm

EDGE

CEPPO
UB55

TYPE: ABS
HEIGHT: from 15 to 350 mm
THICKNESS: from 0.5 to 2.0 mm